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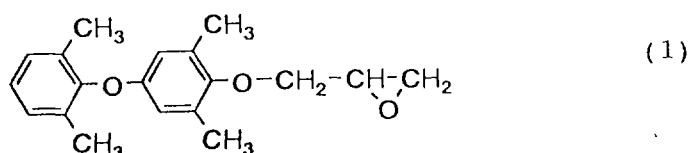
## EPOXY RESIN COMPOSITION AND PROCESS FOR PRODUCING THE SAME

## Abstract

The present invention provides a tetramethylbiphenyl type high performance epoxy resin composition and a curable epoxy resin composition containing the epoxy resin, useful in electrical and electronic fields and the like. The tetramethylbiphenyl type epoxy resin composition comprises an epoxy resin composition obtained by reacting 4,4'-dihydroxy-3,3',5,5'-tetramethylbiphenyl and an epihalohydrin in the presence of an alkali metal hydroxide. The composition has a content of tetramethyldiphenylquinone of 0.5% by weight or less and a content of glycidyl compound represented by the following structural formula (1):



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of 0.5% by weight or less. The curable epoxy resin composition contains the epoxy resin composition and a hardener for the epoxy resin.